

## Solder Spheres for BGAs

### Product Highlights

Chip Quik® BGA solder spheres are manufactured from virgin materials to meet or exceed the requirements of building or repairing BGA packages. Chip Quik® BGA solder spheres also exceed both the IPC and MIL standards for purity levels and size tolerances. Nominal sizes are available from 12 to 30 mil.

### Product Specifications

Part Number	Alloy	Melting Point	Diameter	Quantity (by weight)
SMD2165	Sn63/Pb37	183°C (361°F)	0.012" (0.305mm)	250,000
SMD2165-25000	Sn63/Pb37	183°C (361°F)	0.012" (0.305mm)	25,000
SMD2190	Sn63/Pb37	183°C (361°F)	0.020" (0.508mm)	250,000
SMD2190-25000	Sn63/Pb37	183°C (361°F)	0.020" (0.508mm)	25,000
SMD2200	Sn63/Pb37	183°C (361°F)	0.024" (0.610mm)	250,000
<b>SMD2200-25000</b>	<b>Sn63/Pb37</b>	<b>183°C (361°F)</b>	<b>0.024" (0.610mm)</b>	<b>25,000</b>
SMD2205	Sn63/Pb37	183°C (361°F)	0.025" (0.635mm)	250,000
SMD2205-25000	Sn63/Pb37	183°C (361°F)	0.025" (0.635mm)	25,000
SMD2215	Sn63/Pb37	183°C (361°F)	0.030" (0.762mm)	250,000
SMD2215-25000	Sn63/Pb37	183°C (361°F)	0.030" (0.762mm)	25,000
SMD2040	Sn96.5/Ag3.0/Cu0.5	217-220°C (423-428°F)	0.020" (0.508mm)	250,000
SMD2040-25000	Sn96.5/Ag3.0/Cu0.5	217-220°C (423-428°F)	0.020" (0.508mm)	25,000
SMD2050	Sn96.5/Ag3.0/Cu0.5	217-220°C (423-428°F)	0.024" (0.610mm)	250,000
SMD2050-25000	Sn96.5/Ag3.0/Cu0.5	217-220°C (423-428°F)	0.024" (0.610mm)	25,000
SMD2055	Sn96.5/Ag3.0/Cu0.5	217-220°C (423-428°F)	0.025" (0.635mm)	250,000
SMD2055-25000	Sn96.5/Ag3.0/Cu0.5	217-220°C (423-428°F)	0.025" (0.635mm)	25,000
SMD2060	Sn96.5/Ag3.0/Cu0.5	217-220°C (423-428°F)	0.030" (0.762mm)	250,000
SMD2060-25000	Sn96.5/Ag3.0/Cu0.5	217-220°C (423-428°F)	0.030" (0.762mm)	25,000

Shelf Life: >24 months

### Test Results

Test J-STD-004 or other requirements as stated	Test Requirement	Result
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials

Conforms to the following Industry Standards:

J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):  
RoHS 2 Directive 2011/65/EU:

Yes  
Yes (Sn96.5/Ag3.0/Cu0.5) /  
No (Sn63/Pb37)